

**/ Descriptions**

TO-92          NPN          Silicon NPN transistor in a TO-92 Plastic Package.

**/ Features**

$h_{FE}$ ,  
Low noise, high  $h_{FE}$ , high breakdown voltage.

**/ Applications**

Low noise audio amplifier application.

**/ Equivalent Circuit**



**/ Pinning**



PIN1 Base          PIN 2 Collector          PIN 3 Emitter

**/  $h_{FE}$  Classifications & Marking**

$h_{FE}$ Classifications Symbol	Y	GR	BL
$h_{FE}$ Range	120~240	200~400	350~700

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	$V_{CBO}$	120	V
Collector to Emitter Voltage	$V_{CEO}$	120	V
Emitter to Base Voltage	$V_{EBO}$	5.0	V
Collector Current - Continuous	$I_C$	100	mA
Collector Power Dissipation	$P_C$	625	mW
Junction Temperature	$T_j$	150	
Storage Temperature Range	$T_{stg}$	-55 150	

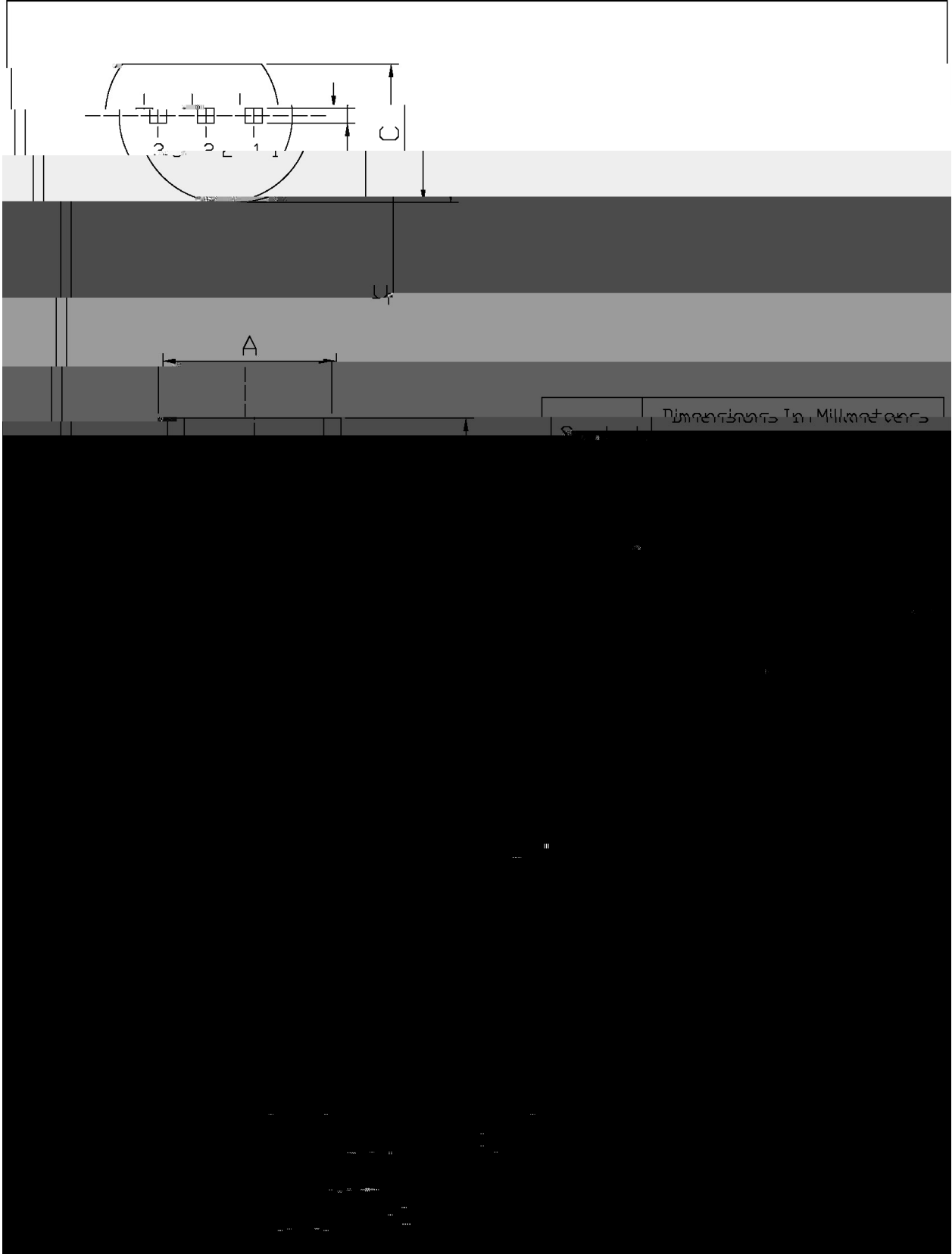
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Base Breakdown Voltage	$V_{CBO}$	$I_C=1.0mA$ $I_B=0$	120			V
Collector to Emitter Breakdown Voltage	$V_{CEO}$	$I_C=100 A$ $I_E=0$	120			V
Emitter to Base Breakdown Voltage	$V_{EBO}$	$I_E=100 A$ $I_C=0$	5.0			V
Collector Cut-Off Current	I					



/ Package Dimensions

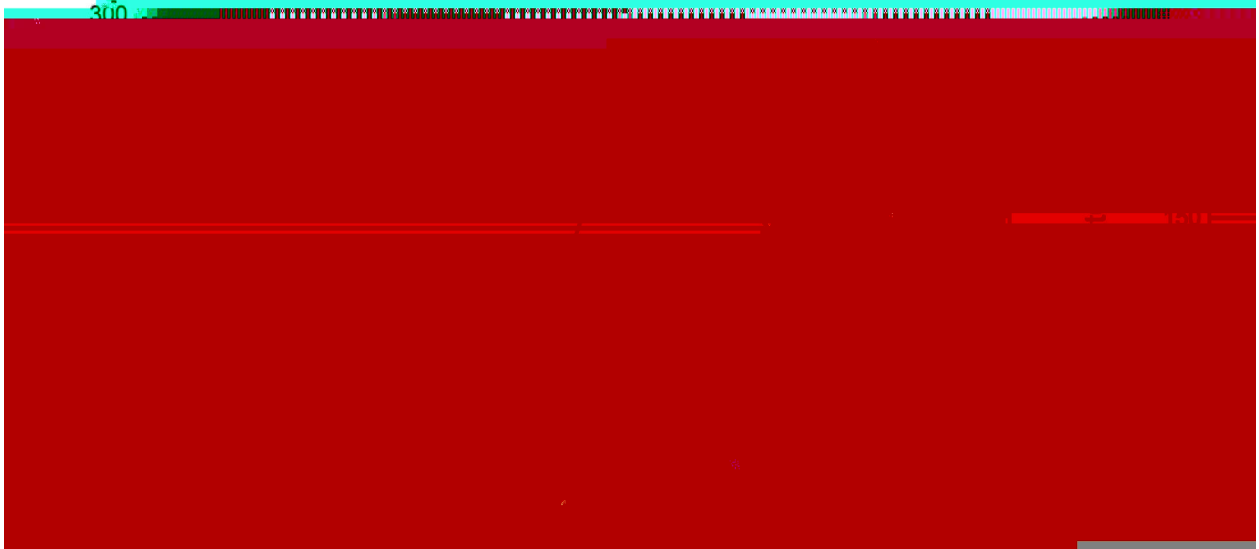
T0-92

Unit: mm





**( ) / Temperature Profile for Dip Soldering(Pb-Free)**



- |   |       |     |           |        |   |                                      |
|---|-------|-----|-----------|--------|---|--------------------------------------|
| 1 | 25    | 150 | 60        | 90sec; | Note:                                   | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 255±5 |     | 5±0.5sec; |        | 2.Peak Temp.:255±5 , Duration:5±0.5sec. |                                      |
| 3 |       | 2   | 10        | /sec.  | 3. Cooling Speed: 2~10 /sec.            |                                      |

**/ Resistance to Soldering Heat Test Conditions**

270±5                      10±1 sec.                      Temp:270±5                      Time:10±1 sec

**/ Packaging SPEC.**

/ BULK

Package Type	Units				Dimension			(unit mm <sup>3</sup> )

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